DE3S062D

Silicon epitaxial planar type

For ESD protection

■ Features

- High electrostatic discharge ESD
- Halogen-free / RoHS compliant (EU RoHS / UL-94 V-0 / MSL: Level 1 compliant)

■ Marking Symbol: 41

■ Packaging

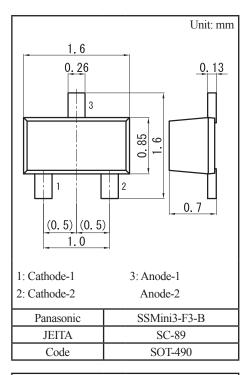
DE3S062D0L Embossed type (Thermo-compression sealing): 3 000 pcs / reel (standard)

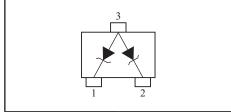
■ Absolute Maximum Ratings $T_a = 25$ °C

Parameter	Symbol	Rating	Unit	
Total power dissipation *1	P_{T}	150	mW	
Electrostatic discharge *2	ESD	±30	kV	
Junction temperature	Tj	150	°C	
Storage temperature	T _{stg}	-55 to +150	°C	

Note) $*1: P_T = 150 \text{ mW}$ achieved with a printed circuit board. (2 Diode total)

^{*2:} Test method: IEC61000-4-2 (C = 150 pF, R = 330 Ω , Contact discharge: 10 times)



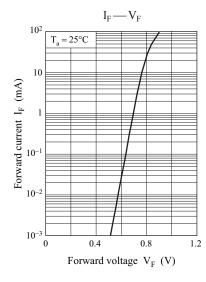


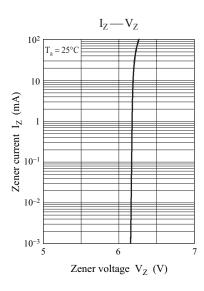
■ Common Electrical Characteristics $T_a = 25$ °C±3°C

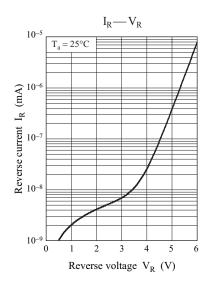
Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Zener voltage *1,2	V _Z	$I_Z = 1 \text{ mA}$	5.89		6.51	V
Reverse current	I_R	$V_R = 4 V$			1	μΑ
Terminal capacitance	C _t	$V_R = 0 V, f = 1 MHz$		55		pF
Temperature coefficient of zener voltage *3	S_Z	$I_Z = 1 \text{ mA}$		2.3		mV/°C

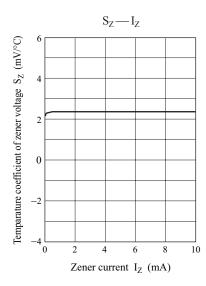
Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.

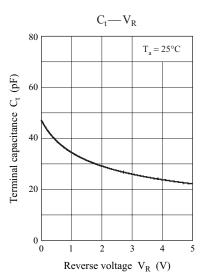
- 2. *1: The temperature must be controlled 25°C for V_Z measurement. V_Z value measured at other temperature must be adjusted to V_Z (25°C)
 - *2: V_Z guaranteed 20 ms after current flow.
 - *3: $T_j = 25$ °C to 150°C







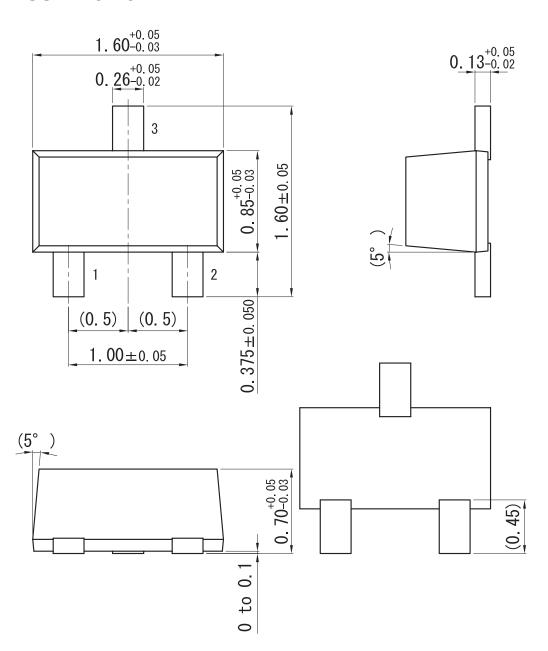




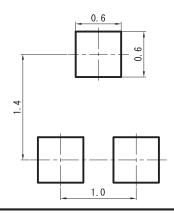
Ver. BED 2

SSMini3-F3-B

Unit: mm



■ Land Pattern (Reference) (Unit: mm)



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